

LM136-2.5-N, LM236-2.5-N, LM336-2.5-NV Reference Diode

 Check for Samples: [LM136-2.5-N](#)

FEATURES

- **Low Temperature Coefficient**
- **Wide Operating Current of 400 μ A to 10 mA**
- **0.2 Ω Dynamic Impedance**
- **\pm 1% Initial Tolerance Available**
- **Specified Temperature Stability**
- **Easily Trimmed for Minimum Temperature Drift**
- **Fast Turn-On**

DESCRIPTION

The LM136-2.5-N/LM236-2.5-N and LM336-2.5-N integrated circuits are precision 2.5V shunt regulator diodes. These monolithic IC voltage references operate as a low-temperature-coefficient 2.5V zener with 0.2 Ω dynamic impedance. A third terminal on the LM136-2.5-N allows the reference voltage and temperature coefficient to be trimmed easily.

The LM136-2.5-N series is useful as a precision 2.5V low voltage reference for digital voltmeters, power supplies or op amp circuitry. The 2.5V make it convenient to obtain a stable reference from 5V logic supplies. Further, since the LM136-2.5-N operates as a shunt regulator, it can be used as either a positive or negative voltage reference.

The LM136-2.5-N is rated for operation over -55°C to $+125^{\circ}\text{C}$ while the LM236-2.5-N is rated over a -25°C to $+85^{\circ}\text{C}$ temperature range.

The LM336-2.5-N is rated for operation over a 0°C to $+70^{\circ}\text{C}$ temperature range. See the connection diagrams for available packages.

Connection Diagram

TO-92 Plastic Package

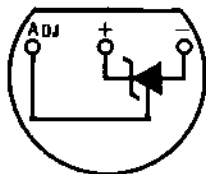


Figure 1. Bottom View
See Package Number LP

TO Metal Can Package

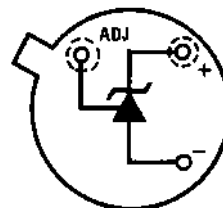


Figure 2. Bottom View
See Package Number NDV

SOIC Package

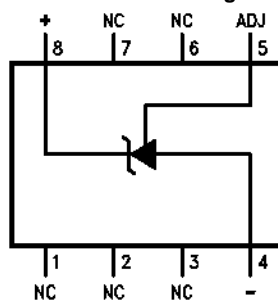


Figure 3. Top View
See Package Number D



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

Typical Applications

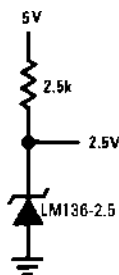
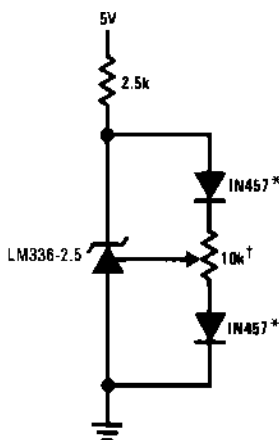


Figure 4. 2.5V Reference



†Adjust to 2.490V

*Any silicon signal diode

Figure 5. 2.5V Reference with Minimum Temperature Coefficient

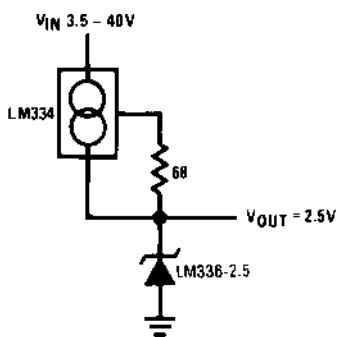


Figure 6. Wide Input Range Reference



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾

Reverse Current		15 mA	
Forward Current		10 mA	
Storage Temperature		-60°C to +150°C	
Operating Temperature Range ⁽³⁾	LM136	-55°C to +150°C	
	LM236	-25°C to +85°C	
	LM336	0°C to +70°C	
Soldering Information	TO-92 Package (10 sec.)	260°C	
	TO Package (10 sec.)	300°C	
	SOIC Package	Vapor Phase (60 sec.)	215°C
		Infrared (15 sec.)	220°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Electrical specifications do not apply when operating the device beyond its specified operating conditions.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) For elevated temperature operation, T_j max is:
 - LM136 150°C
 - LM236 125°C
 - LM336 100°C

Thermal Resistance	TO-92	TO	SOIC
θ_{ja} (Junction to Ambient)	180°C/W (0.4" leads)	440°C/W	165°C/W
	170°C/W (0.125" lead)		
θ_{jc} (Junction to Case)	n/a	80°C/W	n/a

Electrical Characteristics ⁽¹⁾

Parameter	Conditions		LM136A-2.5-N/ LM236A-2.5-N LM136-2.5-N/ LM236-2.5-N			LM336B-2.5-N LM336-2.5-N			Units
			Min	Typ	Max	Min	Typ	Max	
Reverse Breakdown Voltage	$T_A=25^\circ\text{C}$, $I_R=1\text{ mA}$	LM136, LM236, LM336	2.440	2.490	2.540	2.390	2.490	2.590	V
		LM136A, LM236A, LM336B	2.465	2.490	2.515	2.440	2.490	2.540	V
Reverse Breakdown Change With Current	$T_A=25^\circ\text{C}$, $400\ \mu\text{A}\leq I_R\leq 10\text{ mA}$			2.6	6		2.6	10	mV
Reverse Dynamic Impedance	$T_A=25^\circ\text{C}$, $I_R=1\text{ mA}$, $f = 100\text{ Hz}$			0.2	0.6		0.2	1	Ω
Temperature Stability ⁽²⁾	V_R Adjusted to 2.490V $I_R=1\text{ mA}$ Figure 15	$0^\circ\text{C}\leq T_A\leq 70^\circ\text{C}$ (LM336)					1.8	6	mV
		$-25^\circ\text{C}\leq T_A\leq +85^\circ\text{C}$ (LM236H, LM236Z)		3.5	9				mV
		$-25^\circ\text{C}\leq T_A\leq +85^\circ\text{C}$ (LM236M)		7.5	18				mV
		$-55^\circ\text{C}\leq T_A\leq +125^\circ\text{C}$ (LM136)		12	18				mV
Reverse Breakdown Change With Current	$400\ \mu\text{A}\leq I_R\leq 10\text{ mA}$		3	10		3	12	mV	
Reverse Dynamic Impedance	$I_R=1\text{ mA}$		0.4	1		0.4	1.4	Ω	
Long Term Stability	$T_A=25^\circ\text{C}\pm 0.1^\circ\text{C}$, $I_R=1\text{ mA}$, $t = 1000\text{ hrs}$		20			20		ppm	

- (1) Unless otherwise specified, the LM136-2.5-N is specified from $-55^\circ\text{C}\leq T_A\leq +125^\circ\text{C}$, the LM236-2.5-N from $-25^\circ\text{C}\leq T_A\leq +85^\circ\text{C}$ and the LM336-2.5-N from $0^\circ\text{C}\leq T_A\leq +70^\circ\text{C}$.
- (2) Temperature stability for the LM336 and LM236 family is specified by design. Design limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels. Stability is defined as the maximum change in V_{ref} from 25°C to T_A (min) or T_A (max).

Typical Performance Characteristics

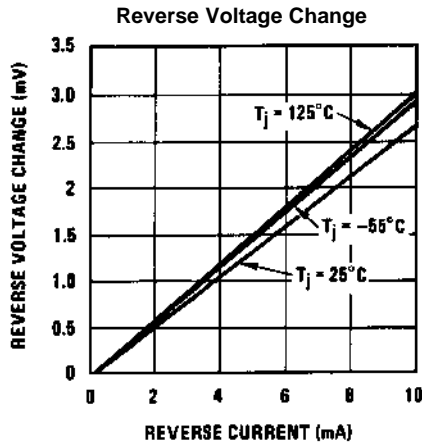


Figure 7.

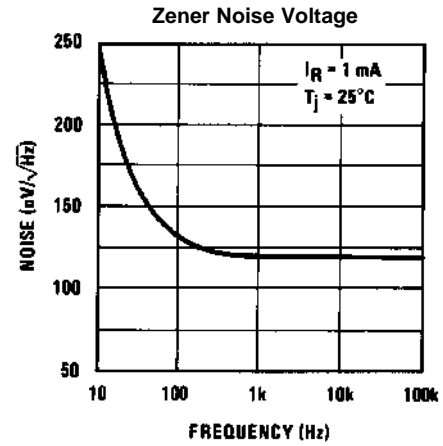


Figure 8.

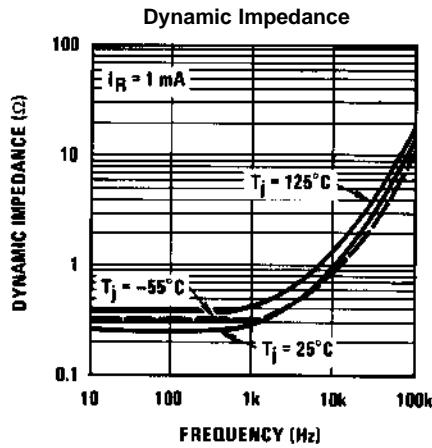


Figure 9.

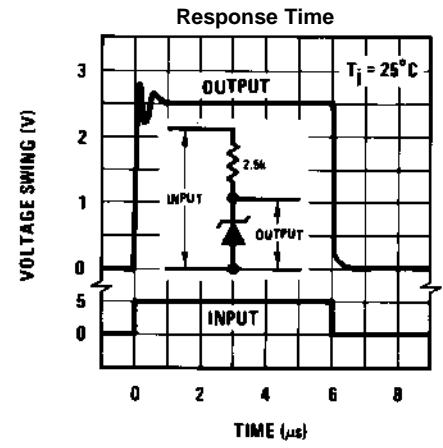


Figure 10.

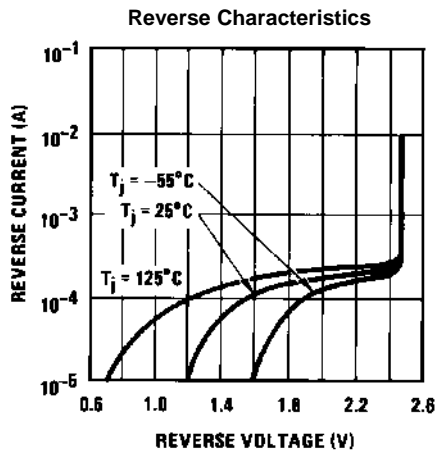


Figure 11.

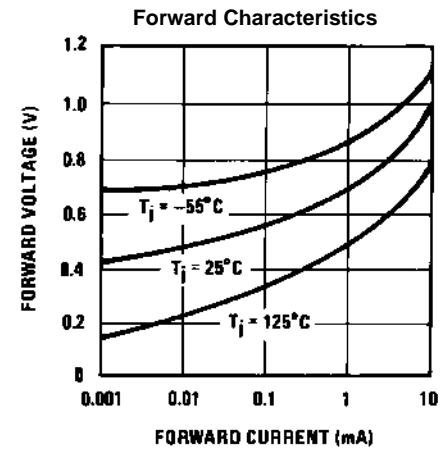
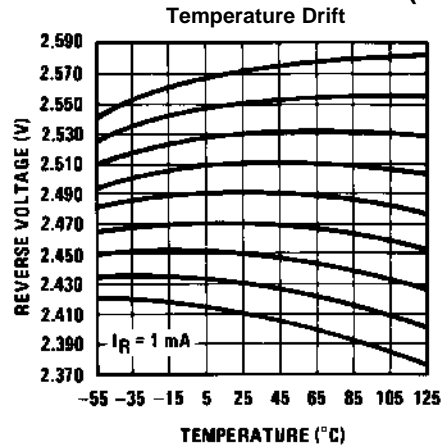


Figure 12.

Typical Performance Characteristics (continued)



APPLICATION HINTS

The LM136 series voltage references are much easier to use than ordinary zener diodes. Their low impedance and wide operating current range simplify biasing in almost any circuit. Further, either the breakdown voltage or the temperature coefficient can be adjusted to optimize circuit performance.

Figure 14 shows an LM136 with a 10k potentiometer for adjusting the reverse breakdown voltage. With the addition of R1 the breakdown voltage can be adjusted without affecting the temperature coefficient of the device. The adjustment range is usually sufficient to adjust for both the initial device tolerance and inaccuracies in buffer circuitry.

If minimum temperature coefficient is desired, two diodes can be added in series with the adjustment potentiometer as shown in Figure 15. When the device is adjusted to 2.490V the temperature coefficient is minimized. Almost any silicon signal diode can be used for this purpose such as a 1N914, 1N4148 or a 1N457. For proper temperature compensation the diodes should be in the same thermal environment as the LM136. It is usually sufficient to mount the diodes near the LM136 on the printed circuit board. The absolute resistance of R1 is not critical and any value from 2k to 20k will work.

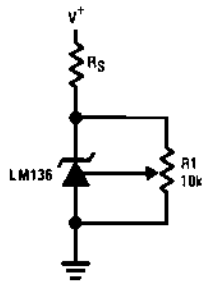


Figure 14. LM136 With Pot for Adjustment of Breakdown Voltage
(Trim Range = ± 120 mV typical)

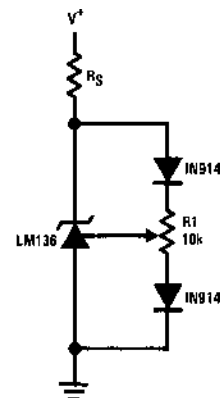
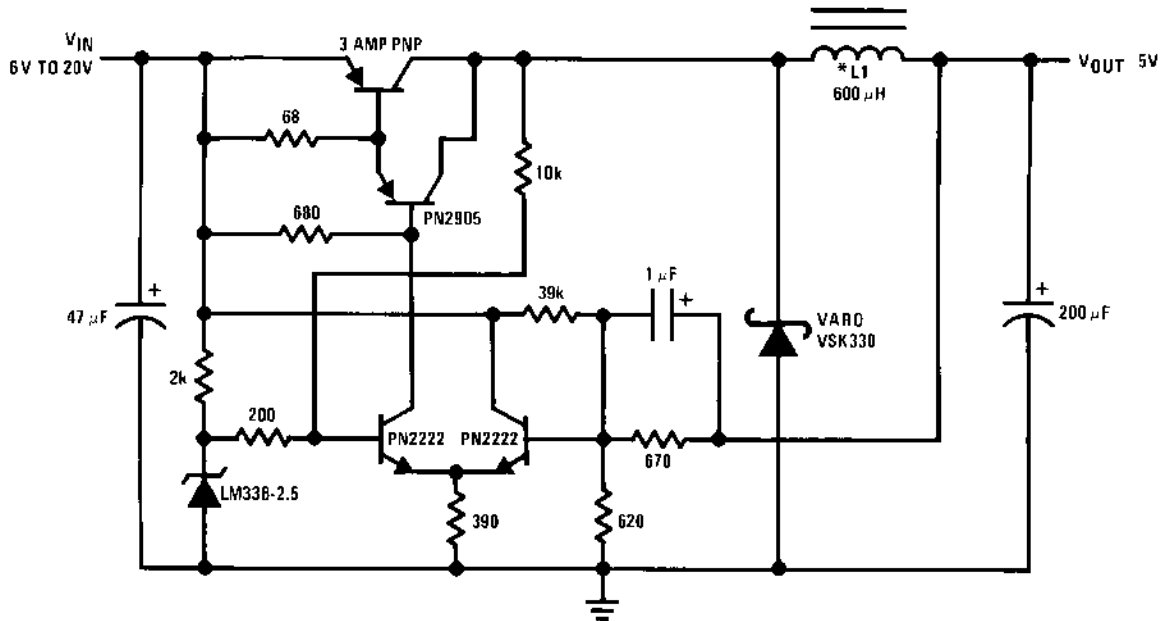


Figure 15. Temperature Coefficient Adjustment
(Trim Range = ± 70 mV typical)



†L1 60 turns #16 wire on Arnold Core A-254168-2
 †Efficiency ≈ 80%

Figure 16. Low Cost 2 Amp Switching Regulator†

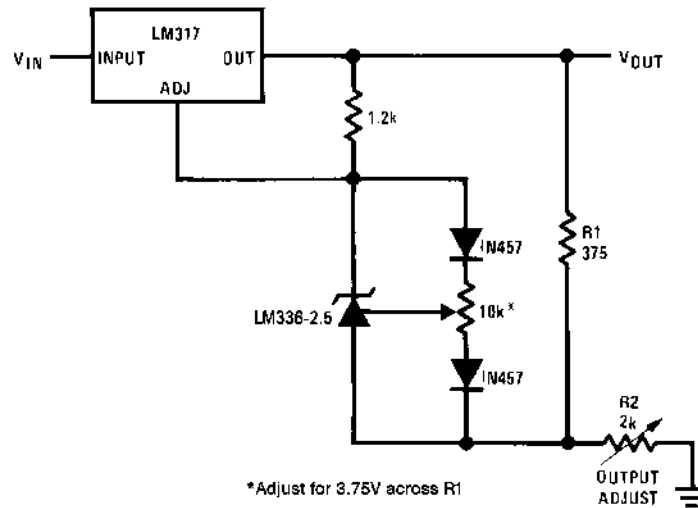


Figure 17. Precision Power Regulator with Low Temperature Coefficient

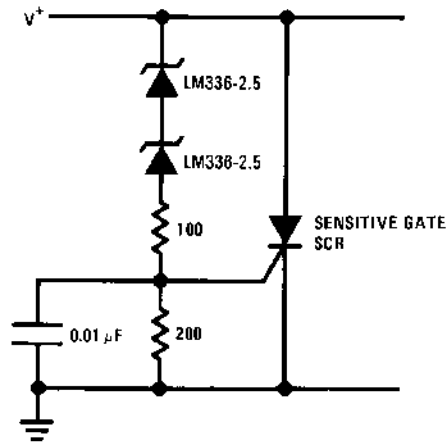
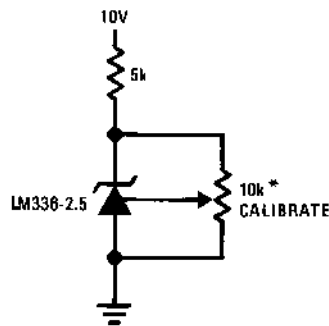


Figure 18. 5V Crowbar



*Does not affect temperature coefficient

Figure 19. Trimmed 2.5V Reference with Temperature Coefficient Independent of Breakdown Voltage

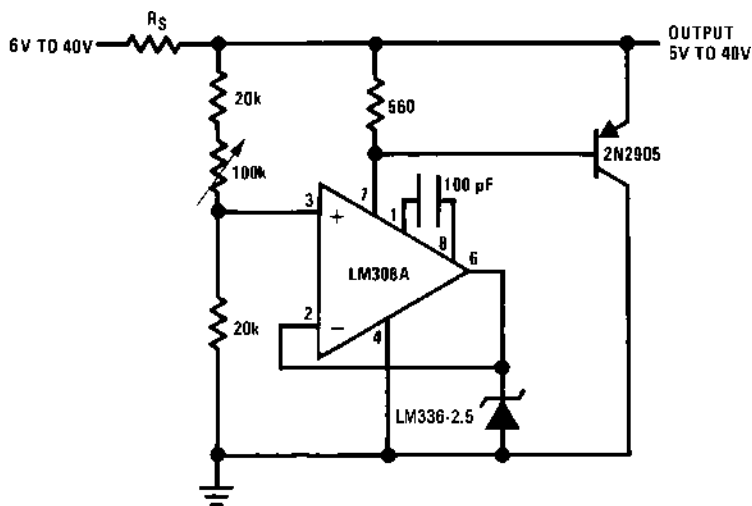


Figure 20. Adjustable Shunt Regulator

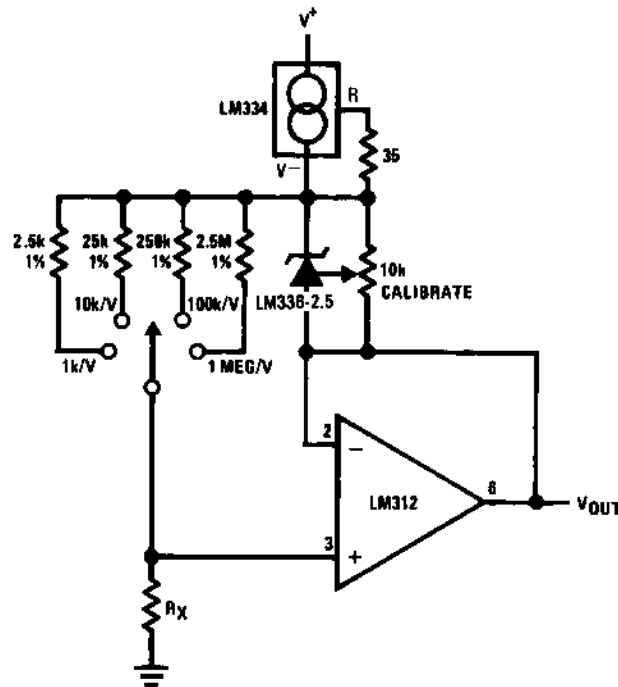


Figure 21. Linear Ohmmeter

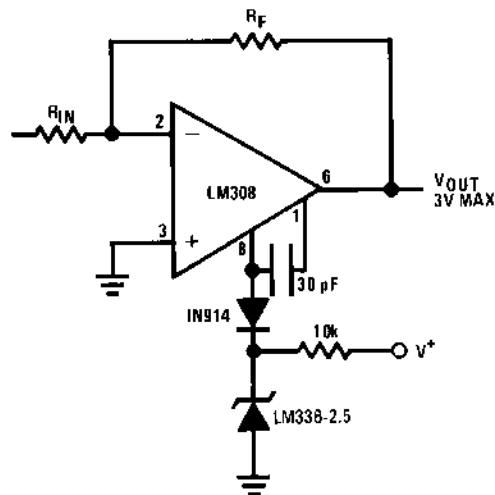


Figure 22. Op Amp with Output Clamped

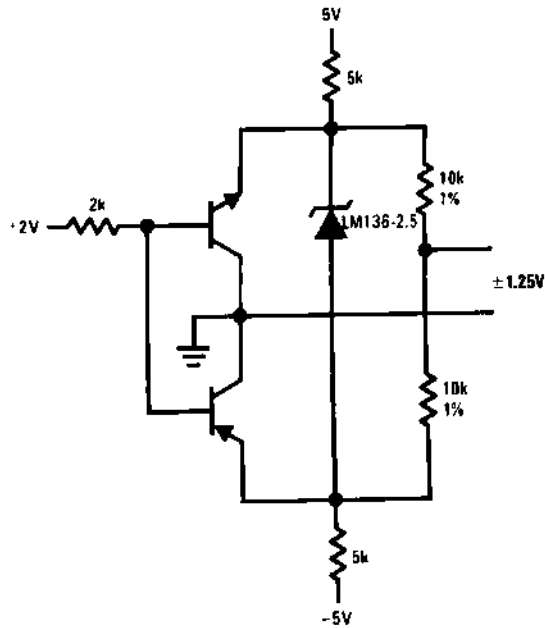


Figure 23. Bipolar Output Reference

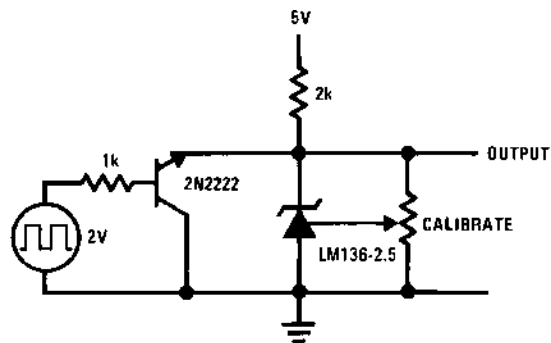


Figure 24. 2.5V Square Wave Calibrator

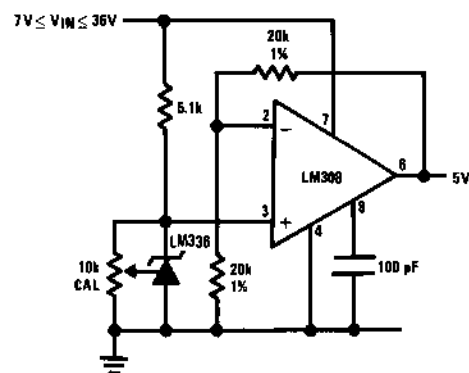


Figure 25. 5V Buffered Reference

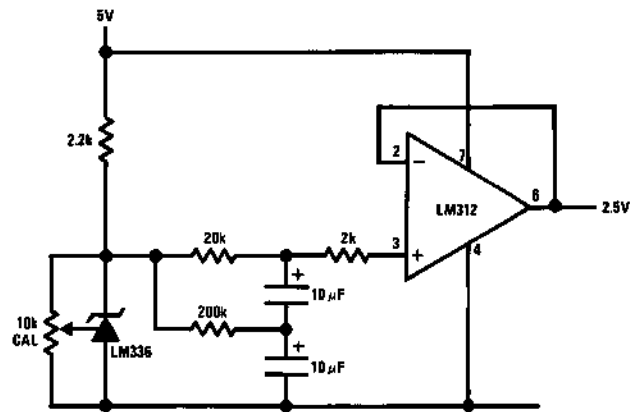
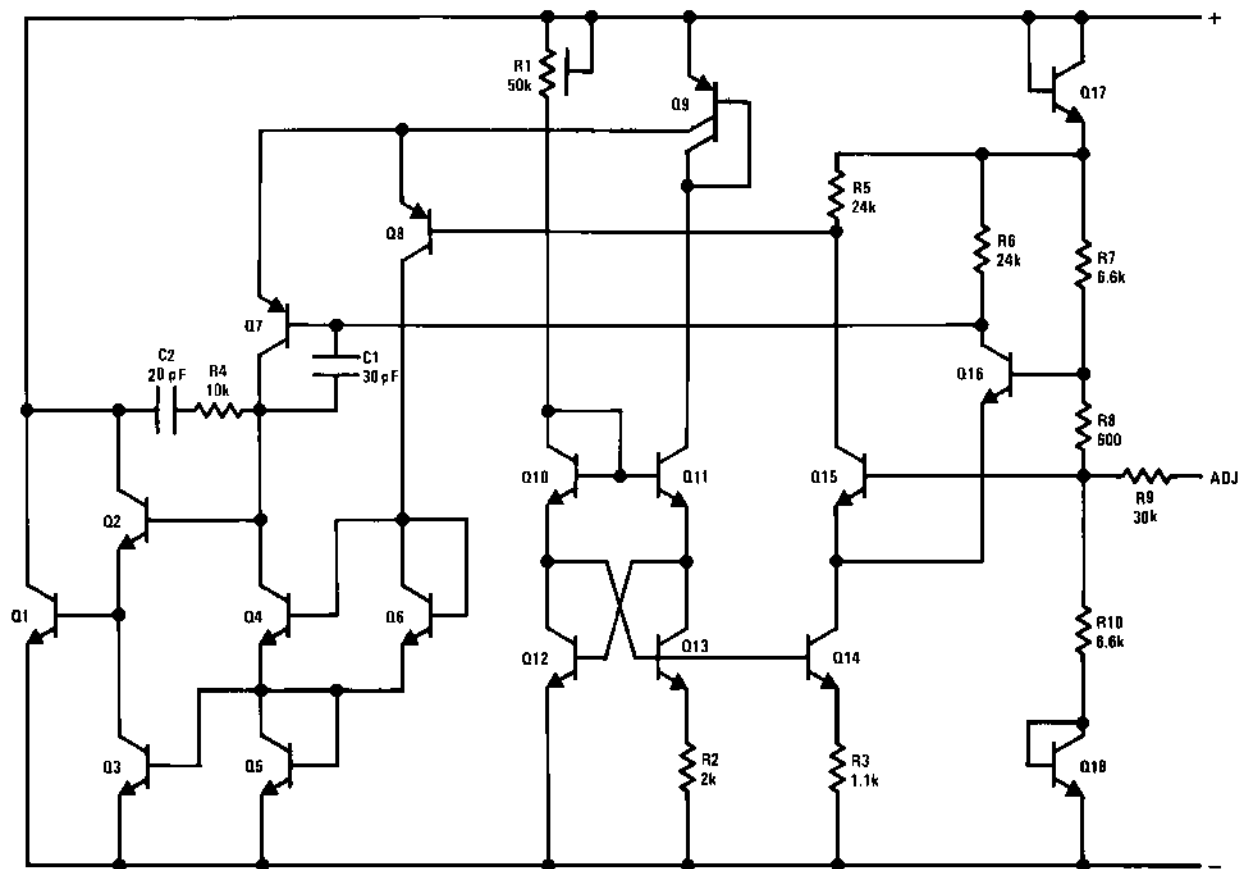


Figure 26. Low Noise Buffered Reference

Schematic Diagram



REVISION HISTORY

Changes from Revision E (April 2013) to Revision F	Page
• Changed layout of National Data Sheet to TI format	11

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM136AH-2.5	ACTIVE	TO	NDV	3	1000	TBD	Call TI	Call TI	-40 to 125	(LM136AH2.5 ~ LM136AH2.5)	Samples
LM136AH-2.5/NOPB	ACTIVE	TO	NDV	3	1000	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 125	(LM136AH2.5 ~ LM136AH2.5)	Samples
LM136H-2.5	ACTIVE	TO	NDV	3	1000	TBD	Call TI	Call TI	-55 to 125	(LM136H2.5 ~ LM136H2.5)	Samples
LM136H-2.5/NOPB	ACTIVE	TO	NDV	3	1000	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-55 to 125	(LM136H2.5 ~ LM136H2.5)	Samples
LM236H-2.5	ACTIVE	TO	NDV	3	1000	TBD	Call TI	Call TI	-25 to 85	(LM236H2.5 ~ LM236H2.5)	Samples
LM236H-2.5/NOPB	ACTIVE	TO	NDV	3	1000	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-25 to 85	(LM236H2.5 ~ LM236H2.5)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

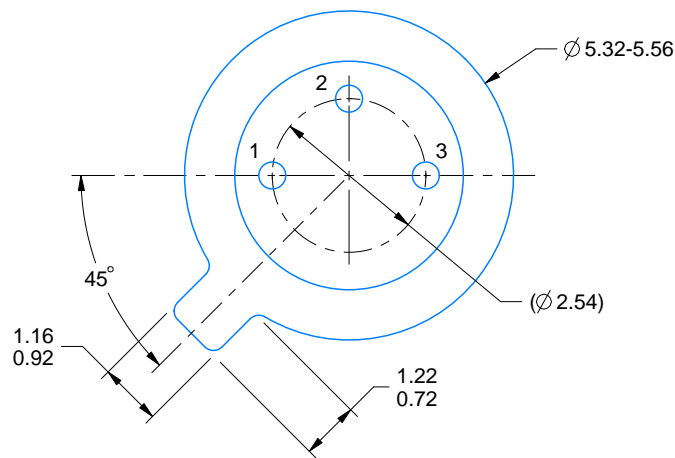
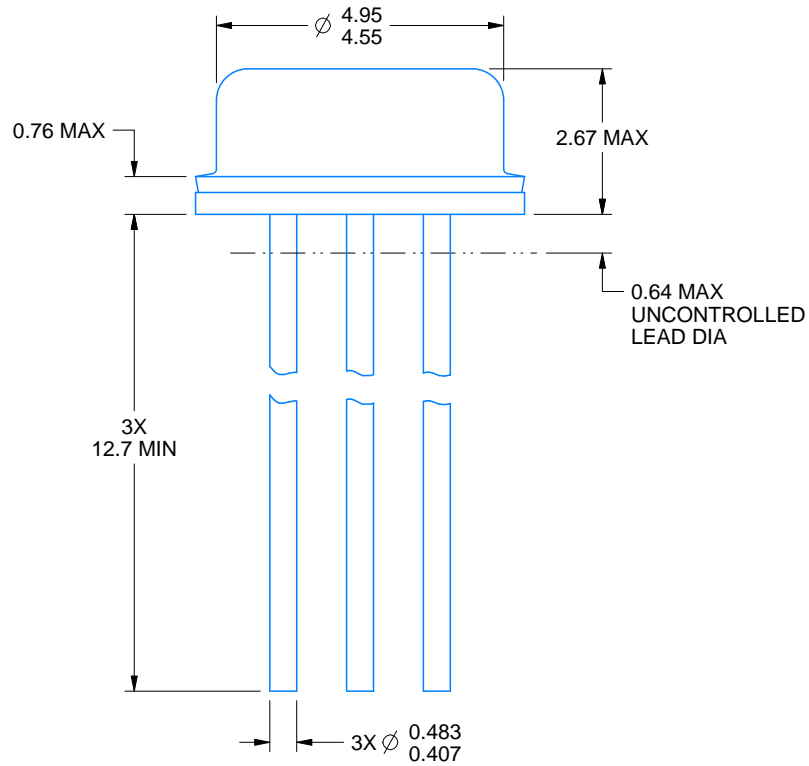
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

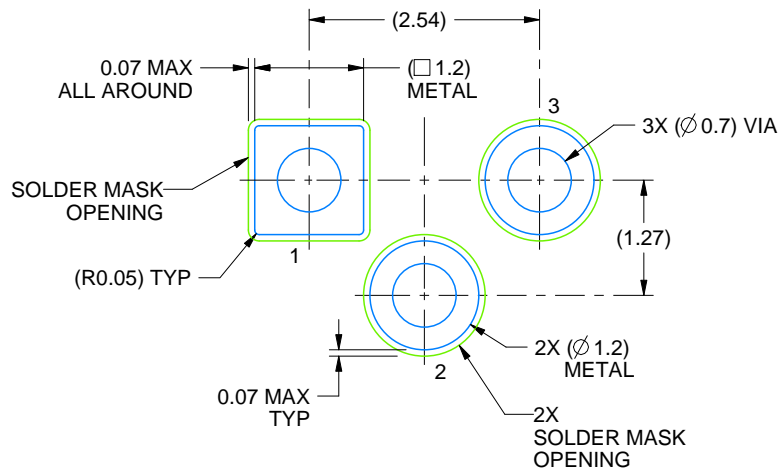
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



4219876/A 01/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-46.



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:12X

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.